

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder and 75/255.cds.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/05/03 09:56
S1	12	("01241395" "01271094" "02211995" "06053645" "09277082" "2000052082" "2001058286" "2002113590" "2002120085" "2003039193" "00568952" "01266987" "2002254195" "00787559").PN.	JPO	OR	OFF	2010/01/14 15:18
S2	0	("0568952" "0787559").PN.	JPO	OR	OFF	2010/01/14 15:22
S3	0	("568952" "787559").PN.	JPO	OR	OFF	2010/01/14 15:22
S4	1	("05068952" "07087559").PN.	JPO	OR	OFF	2010/01/14 15:22
S5	6	("5068952" "7087559" "2004089573").PN.	EPO; DERWENT	OR	OFF	2010/01/14 15:24
S6	6	"568952".PN.	EPO; DERWENT	OR	OFF	2010/01/14 15:26
S7	26	Takaura-Kunihito.inv. and solder	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2010/01/14 15:27
S8	22	Takaura-Kunihito.inv. and solder near paste	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2010/01/14 15:27
S9	4	Takaura-Kunihito.inv. and solder near paste and first	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2010/01/14 15:29

S10	1	"5256370".PN.	USPAT	OR	OFF	2010/01/14 15:49
S17	10	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/14 18:29
S18	96	solder near paste and ((sn tin) near5 (ag silver)) near5 (indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first and second	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/14 18:31
S19	1	"20040177997".PN.	US-PGPUB	OR	OFF	2010/01/14 21:33
S20	10	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near5 powder and first near powder	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/15 10:35
S21	2	("20020040624" "6360939").PN.	US-PGPUB; USPAT	OR	OFF	2010/01/15 10:58
S22	6	solder near paste and ((sn tin) near5 (ag silver)) near5 (indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first and second and 420/557.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/15 11:23
S23	1	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder and 75/252.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/15 11:28

S24	1	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder and 75/255.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/15 11:28
S25	2	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder and "75".clas.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/01/15 11:29
S26	1	"6360939".PN.	USPAT	OR	OFF	2010/01/27 17:25
S27	1	solder near paste and ((sn tin) near5 (ag silver)) near5 (Indium In) and (copper cu) and (bi bismuth) and mix\$4 near2 powder and first near powder and 75/255.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2010/08/22 11:34
S28	4	Takaura-Kunihito.inv. and solder near paste and first	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2011/05/02 14:15

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